



April 9, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

FROM: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 10/685,872
File Date: 10/15/03
Inventor: M. S. Lin
Examiner: Kevin M. Picardat
Art Unit: 2822
Title: Post Passivation Interconnection Schemes On Top Of The
IC Chips
Customer Number: 28112

COMMUNICATION REGARDING ISSUE FEE PAYMENT

This regards the Notice of Allowance dated January 10, 2007 for the above referenced subject patent application. The application had previously been allowed on July 11, 2006 and we paid the Issue Fee on September 18, 2006 at the small entity rate of \$700. Attached is a copy of the post card with the Issue Fee, Publication fee and request for 8 copies paid.

Applicant filed a petition under 37 CFR 1.313 (c) (2) on October 30, 2006, to withdraw the above-mentioned application from issue after payment of the issue fee. The petition was GRANTED.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on April 10, 2007.

Signature

A handwritten signature in black ink, appearing to be "SBA", written over a horizontal line.

STEPHEN B. ACKERMAN, REG. NO. 37,761

Date:

4/10/07

The subject application was subsequently allowed again on January 10, 2007. The Applicant is no longer claiming small entity status. Please see box 5b on the Part B –Fee Transmittal.

Please accept this payment of the Issue Fee.

Respectfully submitted,

A handwritten signature in black ink, appearing to be 'SBA', with a long horizontal flourish extending to the right.

Stephen B. Ackerman
Reg. #37,761

Enclosures

101685,872 10/15/03 M3602-D15A

9/18/06
SEP 27 2006

Post Passivation Interconnection Schemes on

TOP OF THE IC Chips

Issue Fees

700.00 Issue Fee

300.00 Publication Fee

74.00 8 Copies

Filed By M0

